



Material Content Data Sheet



Sales Product Name		SAK-XE162FL-20F66L AA		Issued		25. September 2017		
MA#		MA001053252						
Package		PG-LQFP-64-22		Weight*		369.75 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	17.352	4.69	4.69	46929	46929
leadframe	inorganic material	phosphorus	7723-14-0	0.032	0.01		88	
	non noble metal	zinc	7440-66-6	0.130	0.04		352	
	non noble metal	iron	7439-89-6	2.600	0.70		7031	
wire	non noble metal	copper	7440-50-8	105.558	28.55	29.30	285485	292956
	noble metal	gold	7440-57-5	1.685	0.46	0.46	4558	4558
	encapsulation	organic material	carbon black	1333-86-4	1.150	0.31		3111
encapsulation	plastics	epoxy resin	-	31.057	8.40		83995	
	inorganic material	silicondioxide	60676-86-0	197.845	53.50	62.21	535080	622186
leadfinish	non noble metal	tin	7440-31-5	4.066	1.10	1.10	10996	10996
plating	noble metal	silver	7440-22-4	1.611	0.44	0.44	4356	4356
glue	plastics	epoxy resin	-	1.666	0.45		4505	
	noble metal	silver	7440-22-4	4.997	1.35	1.80	13514	18019
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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